

## 300mA Low Quiescent Current Low-Dropout Linear Regulator

#### **Features**

- Input voltage range: 1.2V to 5.5V
- Fixed outputs of 0.7V, 0.8V, 0.9V, 1.0V, 1.05V,
   1.2V, 1.5V, 1.8V, 2.5V, 2.8V, 3.0V, 3.3V
- Rated output current: 300mA
- Quiescent current: typical 2μA
- Typical 0.1μA shutdown current
- Typical 320mV dropout voltage (Iout=300mA, 1.8V output)
- Power supply rejection ratio: typical 75dB (I<sub>OUT</sub>=30mA, freq=1kHz, 1.8V output)
- Noise: typical 60μVrms (I<sub>OUT</sub>=30mA, BW=10Hz to 100kHz, 1.8V output)
- Built-in output short protection: typical 300mA when output short to ground
- DFN 1mmX1mmX0.37mm-4L package, SOT 23-5L package and DFN 2mmX2mmX0.75mm-6L package

#### **General Description**

AW37103YXXX is a low quiescent current low dropout voltage regulator featuring low ON resistance, high PSRR, low Noise, good load/line transient response and smooth soft-start.

AW37103YXXX integrates current limit, short circuit protection, thermal shutdown, sufficiently protecting IC from being damaged.

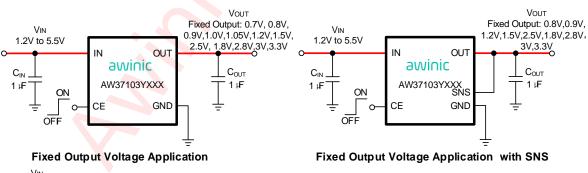
AW37103YXXX is designed to work with a  $1\mu F$  or more input ceramic capacitor and a  $1\mu F$  or more output ceramic capacitor. The low quiescent current make AW37103YXXX very suitable for battery application with long service life. Tiny package makes high density mounting of the IC on boards possible.

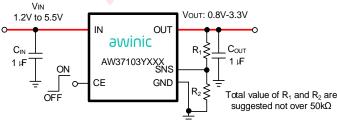
#### **Applications**

Battery-powered equipment Smart phone

Wearables electronics

### **Typical Application Circuit**



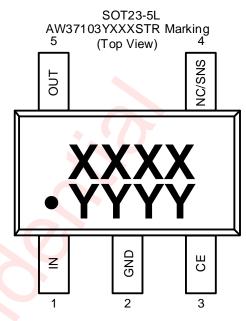


Adjustable Output Voltage Application



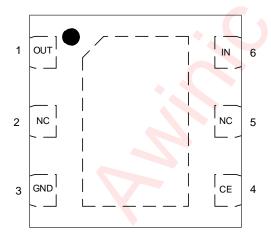
## **Pin Configuration And Top MArk**

# DFN 1 mmX1mmX0.37mm-4L AW37103YXXXDNR (Top View) 1 4 OUT SEXP 2 3 XX – AW37103YXXXDNR Marking XX – AW37103YXXXDNR Y – Production Tracing Code

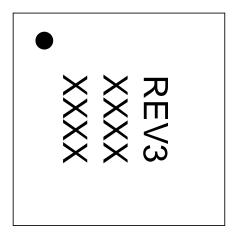


XXXX - AW37103YXXXSTR YYYY - Production Tracing Code

# AW37103D070ADNR (Top View)



# AW37103D070ADNR Marking (Top View)



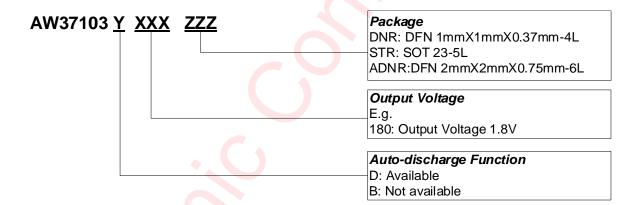
REV3 - AW37103D070ADNR XXXX/XXXX - Production Tracing Code



#### **Pin Definition**

	Pin No.		Pin	DESCRIPTION
DFN1*1-4L	SOT23-5L	DFN2*2-6L	NAME	DESCRIPTION
1	5	1	OUT	Regulated output voltage pin. Put a $1\mu F$ or more ceramic capacitor at the output pin.
2	2	3	GND Ground.	
3	3	4	4 CE Chip enable pin. Built-in 30nA pull (High Active)	
4	1	6	IN	Input supply pin. Put a $1\mu F$ or more bypass capacitor at the power supply.
	4	2,5	NC	No connection.
-	4		SNS	Output voltage sense pin
5	-		EXP	Expose pad should be tied to ground plane for better power dissipation.

#### **Name Rule**



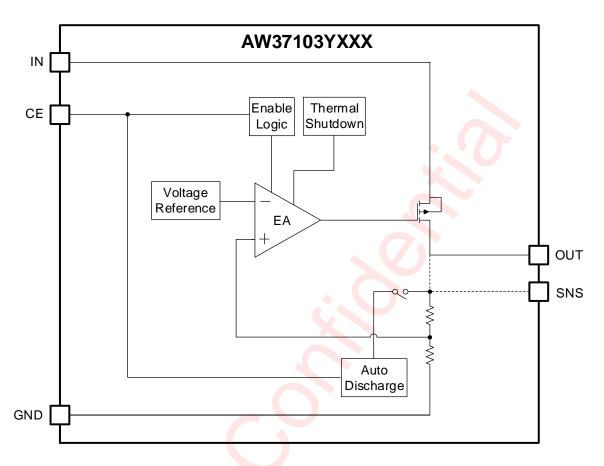


# **Device Comparison Table**

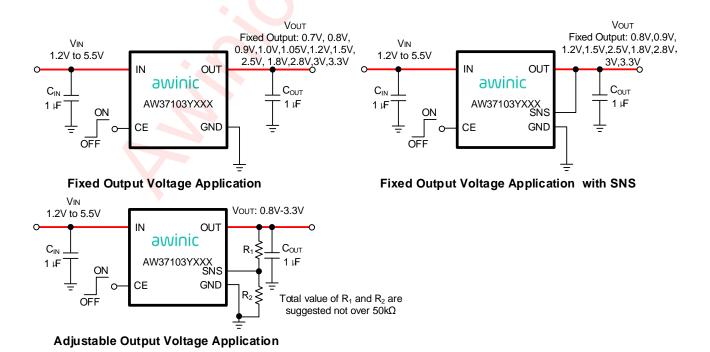
Part Number	V <sub>OUT(SET)</sub>	Rated Current	CE Active	Auto Discharge
AW37103D080DNR	0.8V	300mA	High	YES
AW37103D090DNR	0.9V	300mA	High	YES
AW37103D100DNR	1.0V	300mA	High	YES
AW37103D105DNR	1.05V	300mA	High	YES
AW37103D120DNR	1.2V	300mA	High	YES
AW37103D150DNR	1.5V	300mA	High	YES
AW37103D180DNR	1.8V	300mA	High	YES
AW37103D250DNR	2.5V	300mA	High	YES
AW37103D280DNR	2.8V	300mA	High	YES
AW37103D300DNR	3.0V	300mA	High	YES
AW37103D330DNR	3.3V	300mA	High	YES
AW37103D080STR	0.8V	300mA	High	YES
AW37103D090STR	0.9V	300mA	High	YES
AW37103D120STR	1.2V	300mA	High	YES
AW37103D150STR	1.5V	300mA	High	YES
AW37103D180STR	1.8V	300mA	High	YES
AW37103D250STR	2.5V	300mA	High	YES
AW37103D280STR	2.8V	300mA	High	YES
AW37103D300STR	3.0V	300mA	High	YES
AW37103D330STR	3.3V	300mA	High	YES
AW37103DADJSTR	ADJ	300mA	High	YES
AW37103D070ADNR	0.7V	300mA	High	YES



#### **Functional Block Diagram**



## **Typical Application Circuits**





#### Notice for typical application circuits:

Capacitance of C<sub>IN</sub> and C<sub>OUT</sub> should be 1µF or more.`

A ceramic capacitor has different temperature characteristics and bias dependencies depending on the size, manufacture or part number of a capacitor. Careful evaluation is required. The effective capacitance of  $C_{\text{OUT}}$  should be greater than  $0.7\mu\text{F}$  over the full range of operating conditions. When OUT<1.2V,choose a  $2.2\mu\text{F}$  or more  $C_{\text{OUT}}$ .

For adjustable output voltage application, total value of R1 and R2 are suggested not over 50kΩ.



# **Ordering InformAtion**

Part Number	Temperature	Package	MArking	Moisture Sensitivity Level	Environmenta I InformAtion	Delivery Form
AW37103D080DNR	-40°C∼85°C	DFN 1mmX1mm-4L	CR	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW37103D090DNR	-40°C∼85°C	DFN 1mmX1mm-4L	SW	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW37103D100DNR	-40°C∼85°C	DFN 1mmX1mm-4L	EG	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW37103D105DNR	-40°C∼85°C	DFN 1mmX1mm-4L	FU	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW37103D120DNR	-40°C∼85°C	DFN 1mmX1mm-4L	VF	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW37103D150DNR	-40°C∼85°C	DFN 1mmX1mm-4L	FR	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW37103D180DNR	-40°C∼85°C	DFN 1mmX1mm-4L	FV	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW37103D250DNR	-40°C∼85°C	DFN 1mmX1mm-4L	NN	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW37103D280DNR	-40°C~85°C	DFN 1mmX1mm-4L	YM	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW37103D300DNR	-40°C~85°C	DFN 1mmX1mm-4L	NS	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW37103D330DNR	-40°C~85°C	DFN 1mmX1mm-4L	XN	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW37103D080STR	-40°C~85°C	SOT23-5L	WDTW	MSL3	ROHS+HF	3000 units/ Tape and Reel
AW37103D090STR	-40°C∼85°C	SOT23-5L	H4N5	MSL3	ROHS+HF	3000 units/ Tape and Reel
AW37103D120STR	-40°C∼85°C	SOT23-5L	ZSKN	MSL3	ROHS+HF	3000 units/ Tape and Reel
AW37103D150STR	-40°C∼85°C	SOT23-5L	ZC77	MSL3	ROHS+HF	3000 units/ Tape and Reel



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AW37103D180STR	-40°C∼85°C	SOT23-5L	2JTY	MSL3	ROHS+HF	3000 units/
7470710021000114	10 0 00 0	30120 02	2011	WIGES	1.01.011	Tape and Reel
						3000 units/
AW37103D250STR	-40°C∼85°C	SOT23-5L	0KSU	MSL3	ROHS+HF	Tape and Reel
						3000 units/
AW37103D280STR	-40°C∼85°C	SOT23-5L	QWU5	MSL3	ROHS+HF	Tape and Reel
						3000 units/
AW37103D300STR	-40°C∼85°C	SOT23-5L	F3EK	MSL3	ROHS+HF	Tape and Reel
						3000 units/
AW37103D330STR	-40°C∼85°C	SOT23-5L	U2M0	MSL3	ROHS+HF	Tape and Reel
						3000 units/
AW37103DADJSTR	-40°C∼85°C	SOT23-5L	WZ0V	MSL3	ROHS+HF	Tape and Reel
		DFN				3000 units/
AW37103D070ADNR	-40°C∼85°C	2mmX2mm-6L	REV3	MSL1	ROHS+HF	Tape and Reel



# **Absolute MAximum Ratings**(NOTE1)

PARAMETERS	R	ANGE	
Input voltage range	-0.3V	to 6.5V	
Enable control voltage range	-0.3V	to 6.5V	
Output voltage range	-0.3V to VIN+0	).3V, max. 6.5V	
MAximum operating junction temperature T <sub>JMAX</sub>	150	0°C	
Recommended operating junction temperature T <sub>JREC</sub>	-40°C t	o 125°C	
Operating free-air temperature range	-40°C	to 85°C	
Storage temperature T <sub>STG</sub>	-65°C t	o 150°C	
Lead temperature (soldering 10 seconds)	260°C		
	DFN1*1-4L	232°C/W	
Junction-to-ambient thermal resistance θ <sub>JA</sub> (NOTE2)	SOT23-5L	180°C/W	
	DFN2*2-6L	103°C/W	
ESD			
HBM (Human body model) <sup>(NOTE3)</sup>	±2	kV	
CDM(Charged device model) (NOTE4)	±1.	5kV	
Latch-Up			
Lotob Lip(NOTE5)	+IT: 2	200mA	
Latch-Up <sup>(NOTE5)</sup>	- IT: -	200mA	

NOTE1: Conditions out of those ranges listed in "absolute maximum ratings" may cause permanent damages to the device. In spite of the limits above, functional operation conditions of the device should within the ranges listed in "recommended operating conditions". Exposure to absolute-maximum-rated conditions for prolonged periods may affect device reliability.

NOTE2: Thermal resistance from junction to ambient follows JEDEC 2S2P standards, and is highly dependent on PCB layout.

NOTE3: All pins. Test Condition: ESDA/JEDEC JS-001-2017.

NOTE4: All pins. Test Condition: ESDA/JEDEC JS-002-2018.

NOTE5: Test Condition: JESD78E.



#### **Electrical Characteristics**

 $V_{IN}=V_{OUT(SET)}+1V$ ,  $V_{CE}>1V$ ,  $I_{OUT}=1$ mA,  $C_{IN}=C_{OUT}=1$  $\mu$ F,  $T_A=25$ °C (unless otherwise noted)

PAF	RAMETER	TEST CONDITION	MIN	TYP	MAX	UNIT
V <sub>IN</sub>	Input Voltage Range		1.2		5.5	V
Vout_acc	Output Voltage Accuracy	T <sub>A</sub> =25°C, Ι <sub>ΟUT</sub> =1mA	-2		2	%
LOAD <sub>Reg</sub>	Load Regulation	1mA≤l <sub>о∪т</sub> ≤300mA	• (	0.5		%
LINE <sub>Reg</sub>	Line Regulation	V <sub>OUT(SET)</sub> +0.5V≤V <sub>IN</sub> ≤5.5V , I <sub>OUT</sub> =1mA		1		mV
		Vout(SET)=1.8V		320		
$V_{dropout}$	Dropout Voltage <sup>(1)</sup>	Vout(SET)=2.8V		203		m)/
<b>v</b> aropout	I <sub>OUT</sub> =300mA	Vout(SET)=3.0V		187		mV
		Vout(SET)=3.3V		179		
Isp	Shutdown Current	V <sub>CE</sub> <0.4V		0.1	1	μΑ
lα	Quiescent Current	I <sub>ουτ</sub> =0mA		2	4	μΑ
Vceh	CE Input Voltage "H"	-40°C ≤T <sub>A</sub> ≤85°C	1			V
Vcel	CE Input Voltage "L"	-40°C ≤T <sub>A</sub> ≤85°C			0.4	V
PSRR	Power Supply Ripple Rejection	Ιουτ=30mA, f=1kHz Vουτ(seτ)=1.8V		75		dB
		V <sub>OUT(SET)</sub> =0.8V		50		
	Output Voltage Noise	Vout(SET)=1.8V		60		
V <sub>N</sub>	Iоит=30mA	Vout(SET)=2.8V		80		μVrms
	BW=10Hz to 100kHz	Vout(SET)=3.0V		84		
		Vout(SET)=3.3V		90		
Icl	Output Current Limit	Vout=90%*Vout(SET)	300			mA
Isc	Short Current Limit	Vout<10%*Vout(SET)		300		mA
VTC	Output Voltage Temperature Coefficient	-40°C ≤T <sub>A</sub> ≤85°C		±100		ppm/° C
Roisc	Auto Discharge Resistance	V <sub>IN</sub> =4.3V, V <sub>CE</sub> <0.4V		80		Ω
ICE	CE Pull Down Current			30		nA
Тѕрн	ThermAl Shutdown Threshold	Temperature Rising		155		°C
T <sub>SDL</sub>	ThermAl Shutdown Reset Threshold	Temperature Falling		130		°C

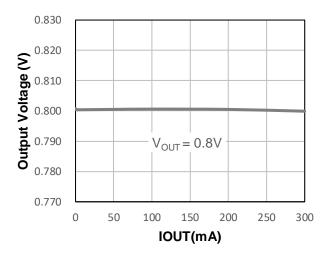
<sup>(1)</sup> Dropout voltage is the voltage difference between the input and the output at which the output voltage drops to 98% of its nominal value.

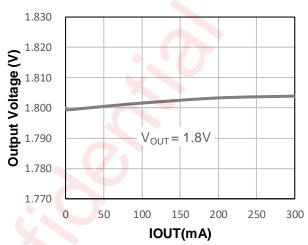


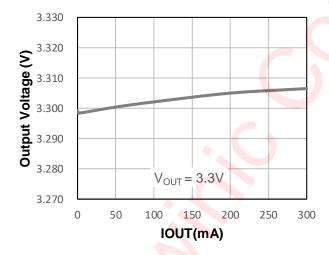
## **Typical Characteristics**

 $V_{\text{IN}}=V_{\text{OUT}(\text{SET})}+1V$ ,  $V_{\text{CE}}>1V$ ,  $I_{\text{OUT}}=1$ mA,  $C_{\text{IN}}=C_{\text{OUT}}=1$  $\mu$ F,  $T_{\text{A}}=25$ °C, In Typical Application Circuit, unless otherwise noted.

1) Ouput Voltage vs. Output Current (C<sub>IN</sub>=C<sub>OUT</sub>=1μF, T<sub>A</sub>=25°C)

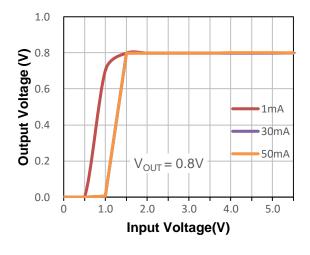


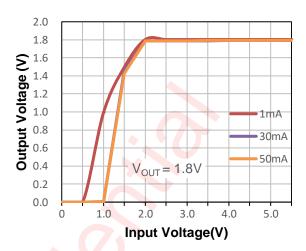


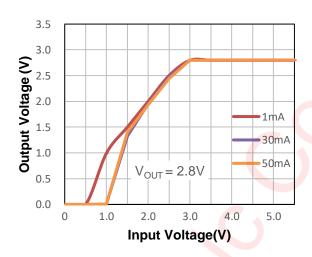


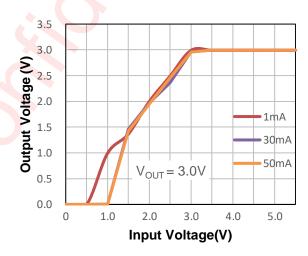


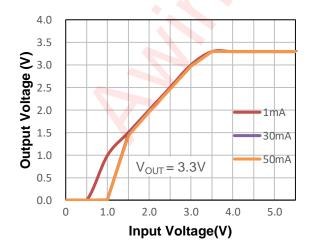
#### 2) Ouput Voltage vs. Input Voltage ( $C_{IN}=C_{OUT}=1\mu F$ , $T_A=25$ °C)





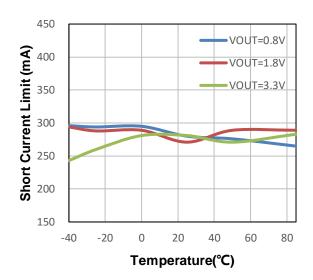




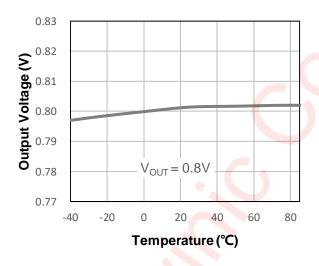


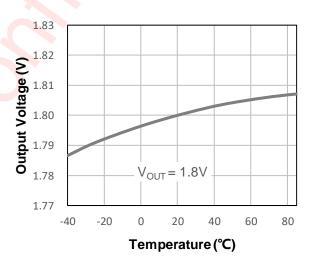


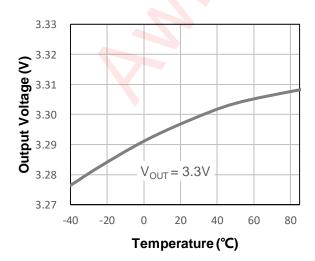
3) Short Current Limit vs. Temperature ( $C_{IN}=C_{OUT}=1\mu F$ )



4) Ouput Voltage vs. Temperature (C<sub>IN</sub>=C<sub>OUT</sub>=1μF, I<sub>OUT</sub>=1MA)

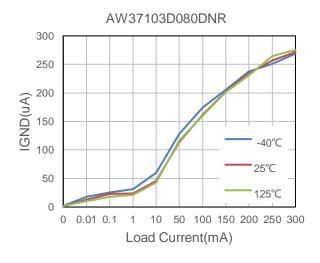


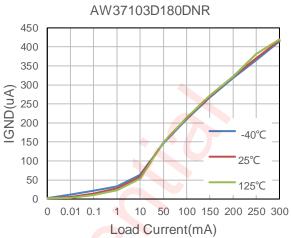


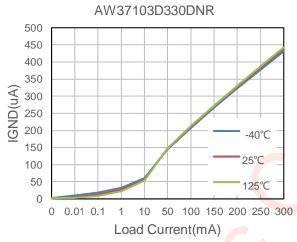




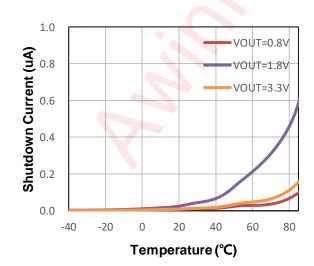
#### 5) Ground Current vs. Load Current ( $C_{IN}=C_{OUT}=1\mu F$ )







#### 6) Shutdown Current vs. Temperature (C<sub>IN</sub>=C<sub>OUT</sub>=1μF)

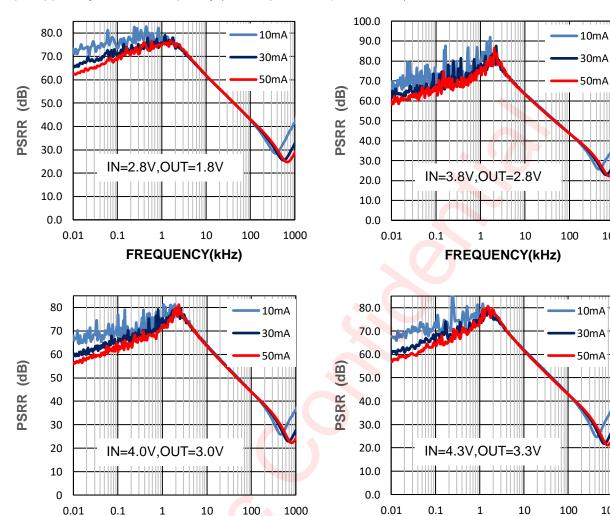


1000

1000

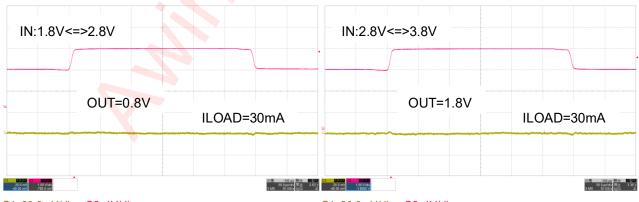


#### 7) Ripple Rejection vs. Frequency (C<sub>IN</sub>=0.1μF,C<sub>OUT</sub>=1μF, T<sub>A</sub>=25°C)



#### 8) Line Transient ( $C_{IN}=C_{OUT}=1\mu F$ , tr = tf =10 $\mu$ s, $T_A=25^{\circ}C$ )

FREQUENCY(kHz)



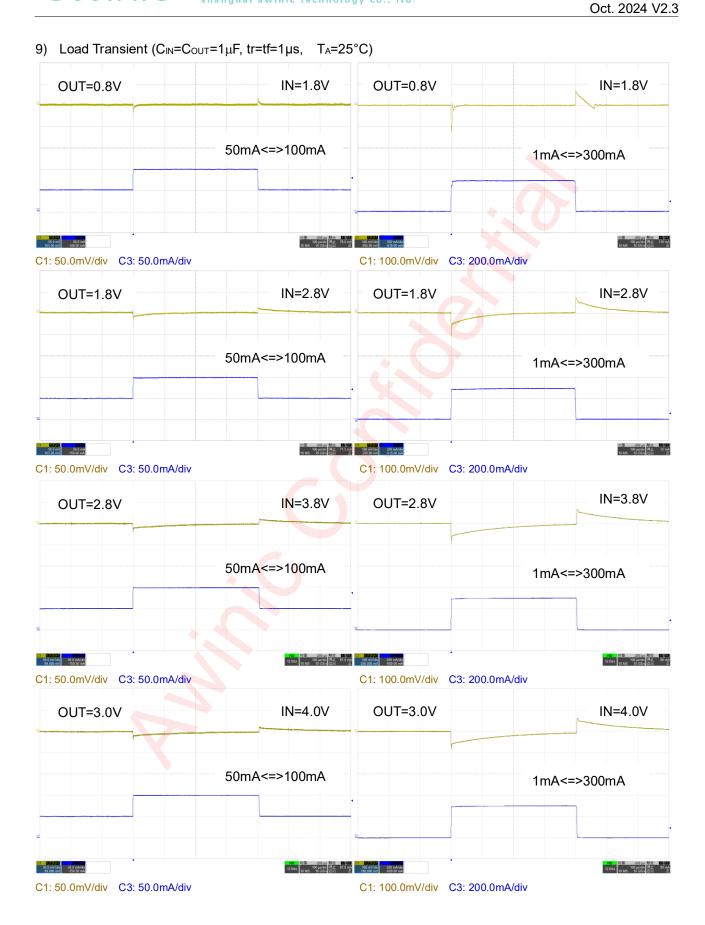
C1: 20.0mV/div C2: 1V/div

FREQUENCY(kHz)









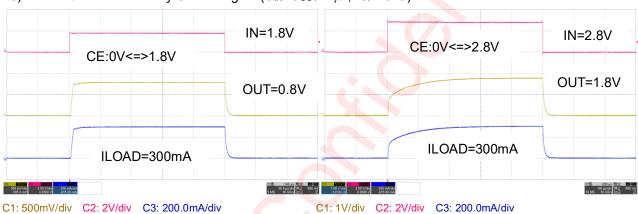


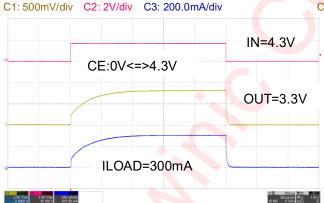
OUT=3.3V IN=4.3V OUT=3.3V IN=4.3V

50mA<=>100mA 1mA<=>300mA

C1: 50.0mV/div C3: 50.0mA/div C3: 200.0mA/div

10) Turn-on/off Waveform by CE Pin signal (C<sub>IN</sub>=C<sub>OUT</sub>=1 $\mu$ F, T<sub>A</sub>=25°C)





C1: 2V/div C2: 5V/div C3: 200.0mA/div

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**awinic** 上海艾为电子技术股份有限公司 shanghai awinic technology co., ltd.

#### **Detailed Functional Description**

AW37103YXXX is a low quiescent current low dropout voltage regulator. After powered on, with CE pin assertion, feedback voltage signal from the integrated resistor network and a voltage related to the voltage reference are transmit to positive input terminal and negative input terminal of an error amplifier (EA) respectively. The output signal of EA is used to control the open-state of power MOSFET. After soft-start, feedback voltage signal compares with the established reference voltage, making output voltage stable and accurate. AW37103YXXX integrates function of load transient accelerating, making LDO obtain excellent dynamic load transient response performance.

AW37103YXXX integrates function of load transient accelerating, making LDO obtain excellent dynamic load transient response performance, and when V<sub>IN</sub> is less than V<sub>OUT</sub> SET, IQ will increase significantly.

#### **Enable Operation**

AW37103YXXX uses CE pin to realize enable operation. Applying proper value of voltage to CE pin can make IC enable/disable.

If the voltage of CE pin is less than 0.4V, AW37103YXXX is guaranteed to be disabled. In this state, function modules of IC and power MOSFET are turned off. And the auto discharge function is enabled making output discharge through a on-state NMOSFET to Ground. In disable state, the ground current is reduced to a maximum of 0.5µA.

If the voltage of CE pin is more than 1V, AW37103YXXX is guaranteed to be enabled. In this state, the auto discharge function is disabled, and AW37103YXXX regulates output voltage to the designed value of voltage.

A 30nA pull down current to Ground is built-in at CE pin, making sure that the IC is disabled when CE pin floats. If Enable function is not required, CE pin should be connected directly to IN pin.

#### Adjustable Output Voltage Setting

Because of the small input current at the SNS pin, the AW37103YXXX with SNS pin also can work as an adjustable output voltage LDO. When SNS pin connected to the resistor divider the output voltage is the nominal output voltage multiplied by the resistors divider ratio, see following equation.

$$V_{OUT\_ADJ} = V_{OUT\_SET} \left( 1 + \frac{R1}{R2} \right)$$

#### Where:

- V<sub>OUT-ADJ</sub> is output voltage of the circuit with resistor divider
- Vout-set is 0.8V, the LDO's nominal output voltage

The total value of R1 and R2 are suggested not over 50 Kω. Typical application circuits gives the connections for the adjustable output voltage application.

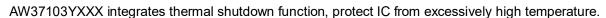
#### **Output Current Limit**

AW37103YXXX integrates output current limit function, protecting IC from excessive current.

When the load is excessively heavy, AW37103YXXX limits the current flowing through the IC to a typical 500mA current. This value is specially designed, so that IC is protected properly and the output capability of 300mA is not influenced either.

Meanwhile, AW37103YXXX integrates a 300mA fold-back current limit function, lowering the system dissipation when output overload or short to Ground.

#### ThermAl Shutdown



When the chip temperature exceeds 155°C and the output current exceeds 50mA, AW37103YXXX detects it as an over-temperature event, triggering thermal shutdown, which will turn off the main function module, including power MOSFET. This inhibits increase of chip's temperature. IC would keep the protection-state on until the chip's temperature falls below to 130°C. At this moment, the over-temperature protection-state is released, IC resumes to work again. The hysteresis avoids IC's turning off and on frequently around the the Thermal Shutdown threshold.

#### **Auto Discharge**

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AW37103YXXX makes output voltage discharge quickly when in CE disable state or thermal shutdown state, benefit from integrating auto discharge function. Auto discharge function is implemented by integrated a NMOSFET of typical  $80\Omega$  Rdson route from Output to Ground, and the route is get through in CE disable state or thermal shutdown state. This feature prevents residual charge voltage on the output capacitor, which may impact proper power up of the system connected to the converter. It should be noted that auto discharge function is optional according to different specs.



#### **Application InformAtion**

#### **Power Dissipation and Device Operation**

The permissible power dissipation is dependent on the ambient temperature T<sub>A</sub> and the junction-to-ambient thermal resistance Roja.

The absolute maximum allowable power dissipation for the device in a given package can be calculated using Equation below, where T<sub>J MAX</sub> = 150°C:

$$PD_{MAX\_ABS} = (T_{J\_MAX} - T_A) / R_{\Theta ja}$$

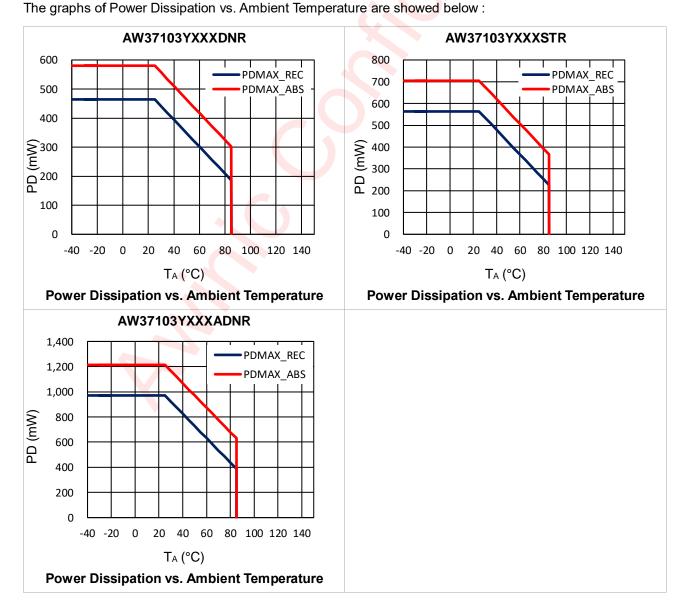
The recommended maximum allowable power dissipation for the device in a given package can be calculated using Equation below, where T<sub>J\_REC</sub> = 125°C:

$$PD_{MAX\_REC} = (T_{J\_REC} - T_A) / R_{\Theta ja}$$

The actual power being dissipated in the device can be represented by Equation below:

$$PD_{ACT} = (V_{IN} - V_{OUT}) \times I_{OUT}$$

These equations above establish the relationship between the maximum power dissipation allowed due to thermal consideration, the voltage drop across the device, and the continuous current capability of the device.





The above graphs show the maximum power dissipation of the respective package at  $T_{J\_REC}$  = 125°C and  $T_{J\_MAX}$  = 150°C. Operating the device in the region between PD<sub>MAX\\_REC</sub> and PD<sub>MAX\\_ABS</sub> might have a negative influence on its lifetime.

#### **Capacitors Selection**

#### IN pin: Input Capacitor CIN

AW37103YXXX advises to use a  $1\mu F$  or more X5R or X7R ceramic capacitor at IN pin as shown in Typical Application Circuit.

#### **OUT pin: Output Capacitor Cout**

AW37103YXXX advises to use a  $1\mu F$  or more X5R or X7R ceramic capacitor at OUT pin as shown in Typical Application Circuit.

#### **Recommended Components List**

Component	PART No.	DESCRIPTION	MFR	TYP.	UNIT
C <sub>IN</sub>	GRM155R61A105KE15	10V, X5R, 0402	MURATA	1	μF
	GRM155R61A105KE15	10V, X5R, 0402	MURATA	1	μF
Соит	GRM153R60J225ME95	6.3V, X5R, 0402	MURATA	2.2	μF
	GRM153R60J475ME15	6.3V, X5R, 0402	MURATA	4.7	μF

#### **PCB Layout Consideration**

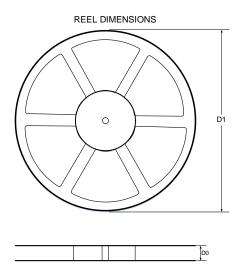
The performance of a power source circuit using this device is highly dependent on a peripheral circuit. To obtain the optimal performance, a peripheral component or the device mounted on PCB should not exceed its rated voltage, rated current or rated power. When designing a peripheral circuit, guidelines below for PCB layout of AW37103YXXX should be obeyed:

- 1. All peripheral components should be placed as close to the chip as possible. C<sub>IN</sub> and C<sub>OUT</sub> should be close to IN and OUT pins respectively. Avoid connecting device and chip pins with two different layers of copper, use the same layer of copper instead.
- 2. IN and OUT pin are the large current input and output of the chip, make IN, OUT, and meanwhile GND lines sufficient.
- 3. The connection lines between the planes of C<sub>IN</sub> or C<sub>OUT</sub> and respective chip pin should be as short and wide as possible, to reduce noise and EMI interference, or it may cause noise pickup or unstable operation.
- 4. The exposed plane of chip and GND pins must be connected to the large-area ground layer of PCB directly, meanwhile place sufficient vias below the exposed plane. Thus we can decrease the thermal resistor on the board to optimize heat-diffusion performance.



# **Tape And Reel InformAtion**

DFN 1mmX1mm-4L

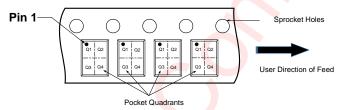


# TAPE DIMENSIONS ко-

- A0: Dimension designed to accommodate the component width
- B0: Dimension designed to accommodate the component length K0: Dimension designed to accommodate the component thickness
- W: Overall width of the carrier tape
  P0: Pitch between successive cavity centers and sprocket hole
- P1: Pitch between successive cavity centers
- P2: Pitch between sprocket hole
  D1: Reel Diameter
- D0: Reel Width

Cavity

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Note: The above picture is for reference only. Please refer to the value in the table below for the actual size

#### DIMENSIONS AND PIN1 ORIENTATION

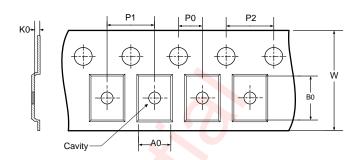
D1	D0	A0	B0	K0	P0	P1	P2	W	Pin1 Quadrant
(mm)	Fiiii Quadrani								
178	8.4	1.14	1.17	0.56	2	4	4	8	Q1

All dimensions are nominal

#### SOT 23-5L

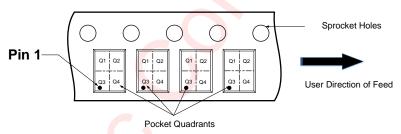
# REEL DIMENSIONS D1 D0

#### TAPE DIMENSIONS



- A0: Dimension designed to accommodate the component width
- B0: Dimension designed to accommodate the component length
- K0: Dimension designed to accommodate the component thickness
- W: Overall width of the carrier tape
- P0: Pitch between successive cavity centers and sprocket hole
- P1: Pitch between successive cavity centers
- P2: Pitch between sprocket hole
- D1: Reel Diameter
- D0: Reel Width

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Note: The above picture is for reference only. Please refer to the value in the table below for the actual size

#### **DIMENSIONS AND PIN1 ORIENTATION**

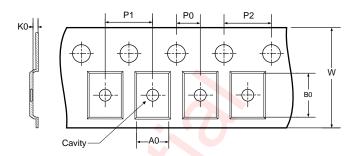
D1	D0	A0	B0	K0	P0	P1	P2	W	Pin1 Quadrant
(mm)	Fini Quadrant								
178	8.4	3.3	3.2	1.4	2	4	4	8	Q3

All dimensions are nominal

#### DFN 2mmX2mm-6L

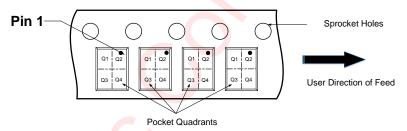
# **REEL DIMENSIONS** 0 D1 DO

#### TAPE DIMENSIONS



- A0: Dimension designed to accommodate the component width B0: Dimension designed to accommodate the component length K0: Dimension designed to accommodate the component thickness
- W: Overall width of the carrier tape
- P0: Pitch between successive cavity centers and sprocket hole
- P1: Pitch between successive cavity centers
- P2: Pitch between sprocket hole
- D1: Reel Diameter
- D0: Reel Width

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Note: The above picture is for reference only. Please refer to the value in the table below for the actual size

#### **DIMENSIONS AND PIN1 ORIENTATION**

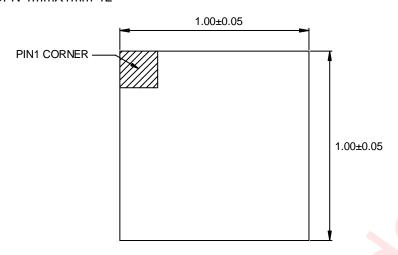
D1	D0	A0	B0	K0	P0	P1	P2	W	Pin1 Quadrant
(mm)	(mm)	(mm)	(mm)	(mm)	(mm)	(mm)	(mm)	(mm)	Pili Quadrant
178.00	8.40	2.30	2.30	1.00	2.00	4.00	4.00	8.00	Q2

All dimensions are nominal

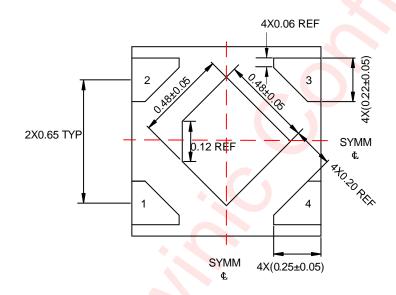


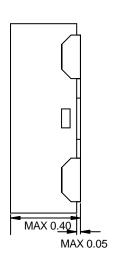
# **Package Description**

DFN 1mmX1mm-4L



**Top View** 



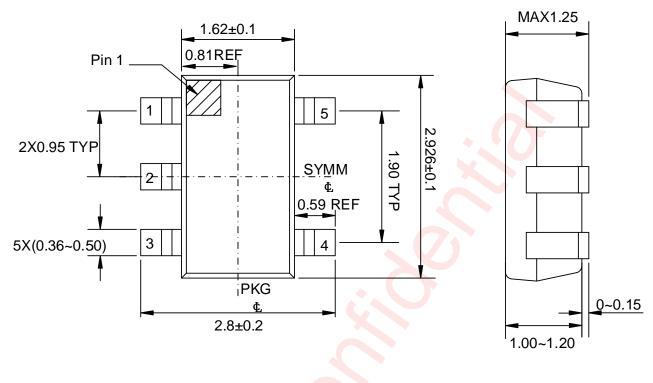


**Bottom View** 

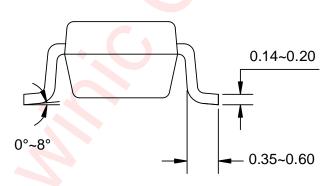
**Side View** 

Unit:mm

SOT 23-5L





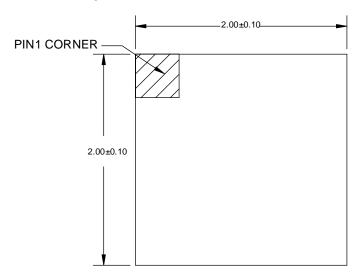


Side View

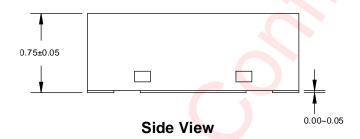
Unit: mm

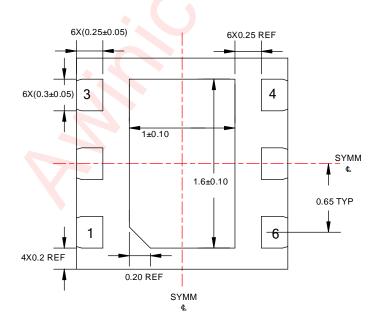
Side View

#### DFN 2mmX2mm-6L



**Top View** 



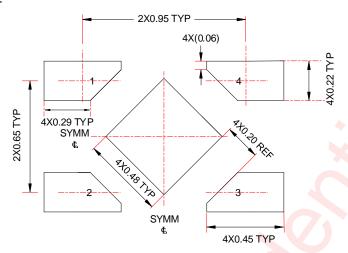


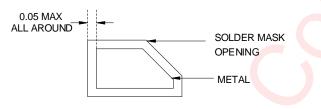
Bottom View Unit: mm

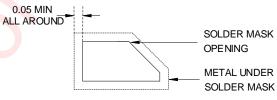


#### **Land Pattern Data**

DFN 1mmX1mm-4L





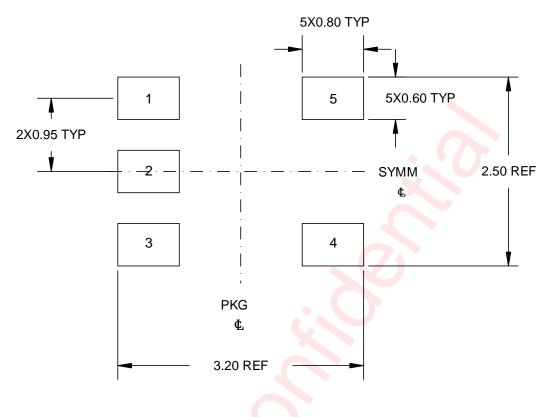


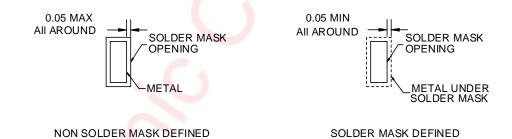
NON SOLDER MASK DEFINED

SOLDER MASK DEFINED

UNIT: mm

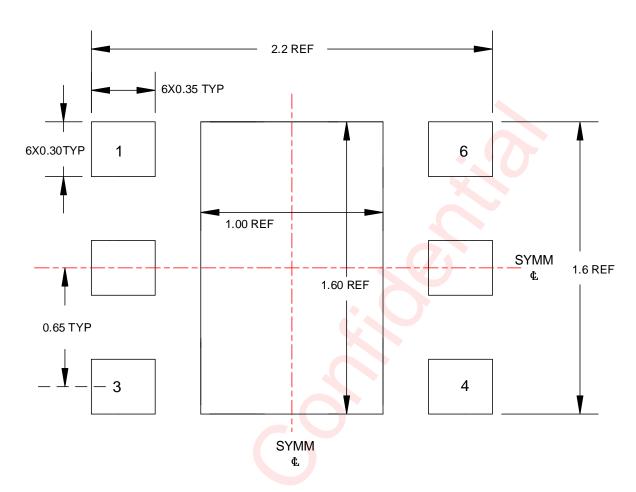
SOT 23-5L



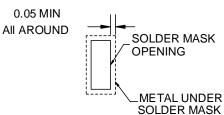


Unit: mm

DFN 2mmX2mm-6L





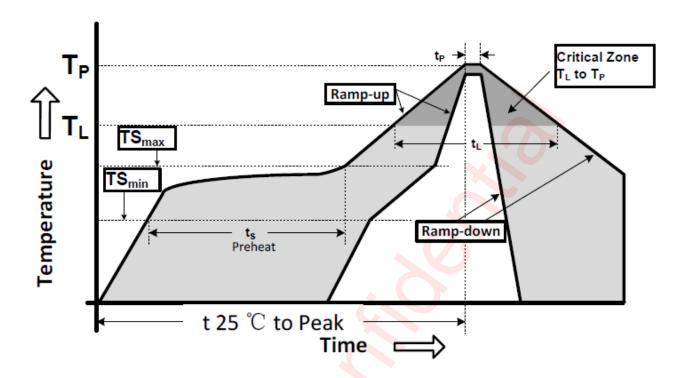


#### **NON SOLDER MASK DEFINED**

#### **SOLDER MASK DEFINED**

Unit: mm

#### **Reflow**



Reflow Note	Spec		
Ramp-up rate(Tsmax to T <sub>P</sub> )	3°C/second max.		
Preheat temperature (Tsmin to Tsmax)	150°C to 200°C		
Preheat time (t <sub>s</sub> )	60 – 180 seconds		
Time above T <sub>L</sub> , 217°C (t <sub>L</sub> )	60 – 150 seconds		
Peak temperature (T <sub>P</sub> )	260°C		
Time within 5°C of peak temperature(t <sub>P</sub> )	20 - 40 seconds		
Ramp-down rate	6°C/second max.		
Time 25°C to peak temperature	8 minutes max.		



# **Revision History**

Version	Date	Change Record
V1.0	Mar. 2021	Officially released
V1.1	Jul. 2021	Add curve: Ground Current vs. Load Current
V1.2	Oct. 2021	Add 2.8V and 3.0V curve
V1.3	Jan. 2022	Add 1.2V edition
V1.4	Jun. 2022	Add max value of Quiescent Current; Add graphs of Power Dissipation vs.  Ambient Temperature; Add reflow curve; Update Tape And Reel Information
V1.5	Aug. 2022	Update SOT 23-5L package description
V1.6	Sep. 2022	Add 1.5V and 2.5V edition
V1.7	Oct. 2022	Add AW37103D080ASTR edition
V1.8	Mar. 2023	Update DFN1mmX1mm-4L package description
V1.9	May. 2023	Change AW37103D080ASTR to AW37103DADJSTR(P4、P7)
V2.0	Jul. 2023	Update "Mv" to "mV"; Update "Ma" to "mA"(P9、P14-17)
V2.1	Aug. 2023	Add 1.0V,1.05V versions for DFN1mmX1mm-4L package(P1 P4-6) Update Name Rule(P3)
V2.2	Jun. 2024	Add 0.7V versions for DFN2mmX2mm-6L package(P1-4 P8-9 P21 P25 P28 P31)
V2.3	Oct. 2024	Update Detailed Functional Description(P19)



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